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Na et al.

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(54) **BATTERY PROTECTION CIRCUIT MODULE PACKAGE**

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(52) **U.S. Cl.**
USPC **D13/119**
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See application file for complete search history.

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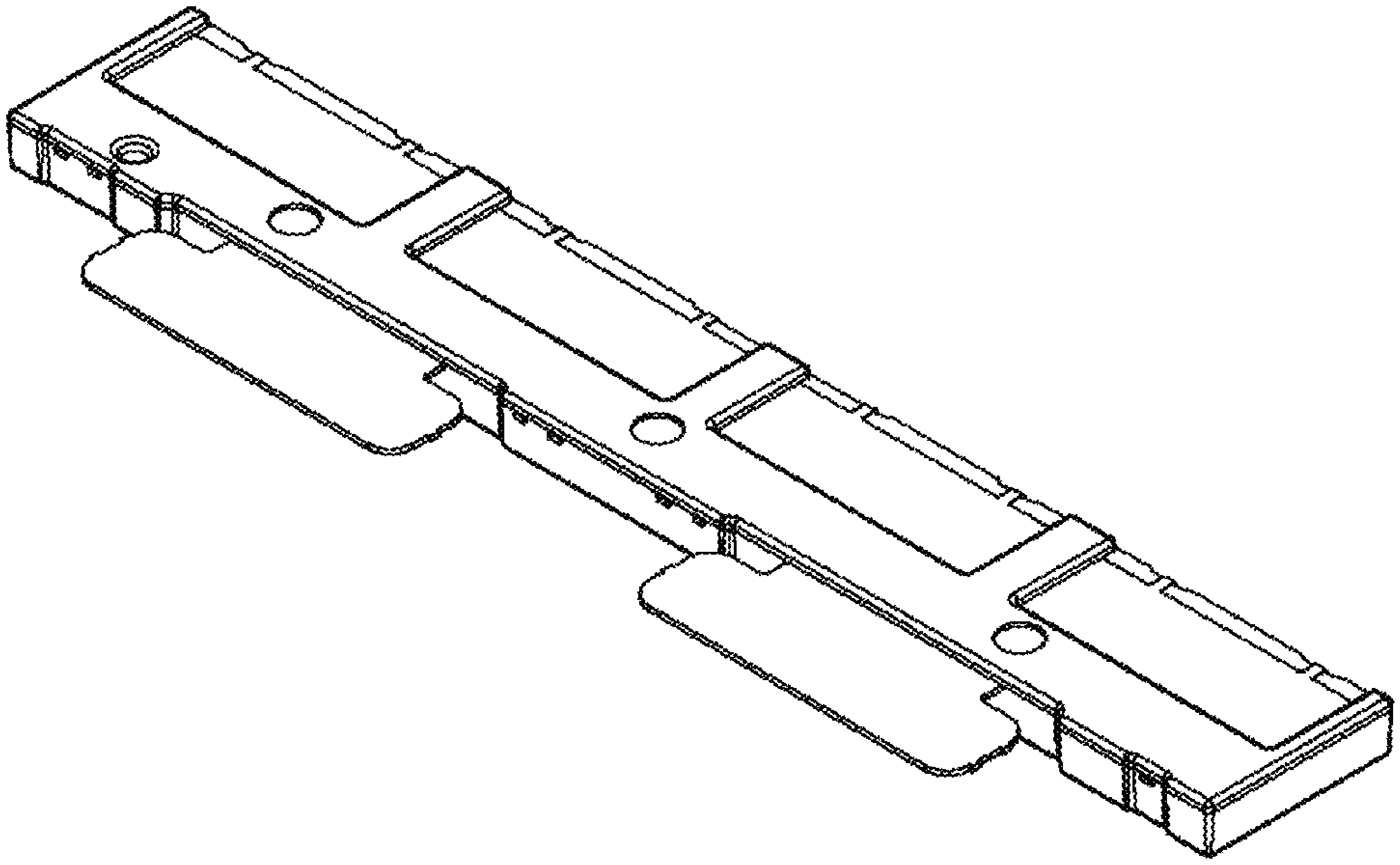
(57) **CLAIM**

We claim the ornamental design for a battery protection circuit module package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a battery protection circuit module package showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 3 Drawing Sheets



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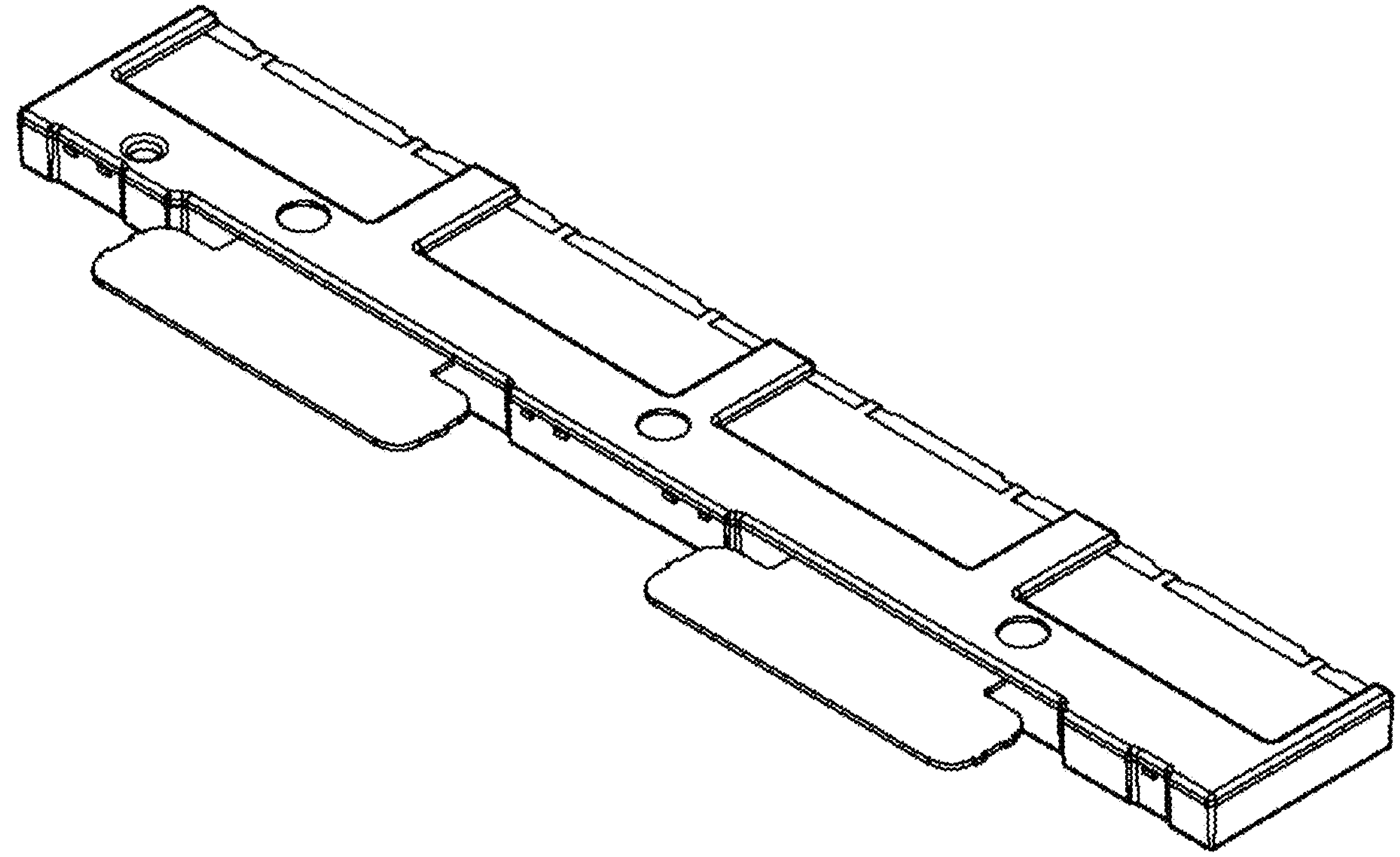

FIG. 1

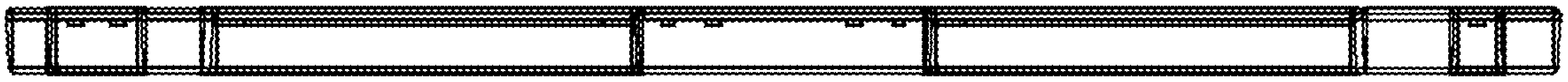

FIG. 2

FIG. 3

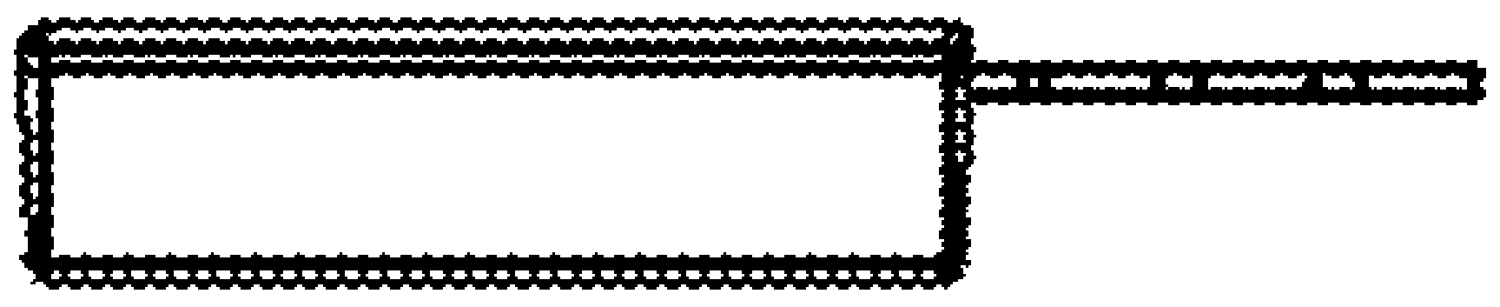

FIG. 4

FIG. 5

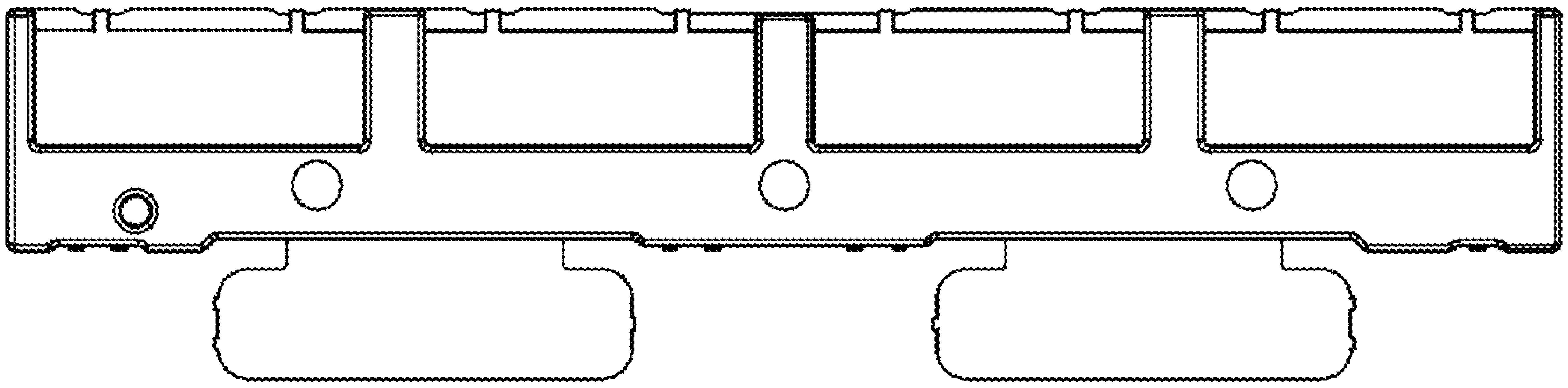

FIG. 6

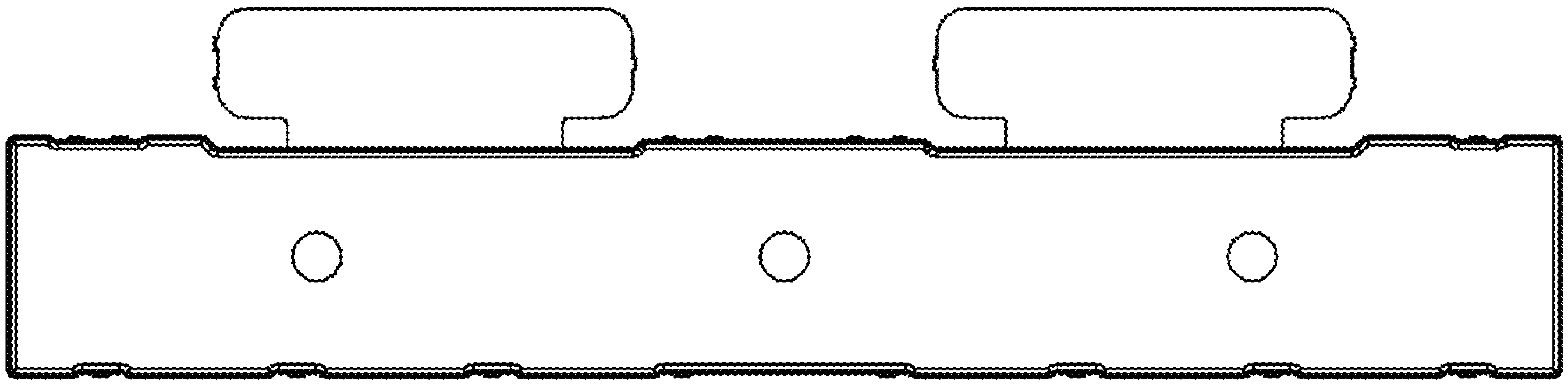

FIG. 7